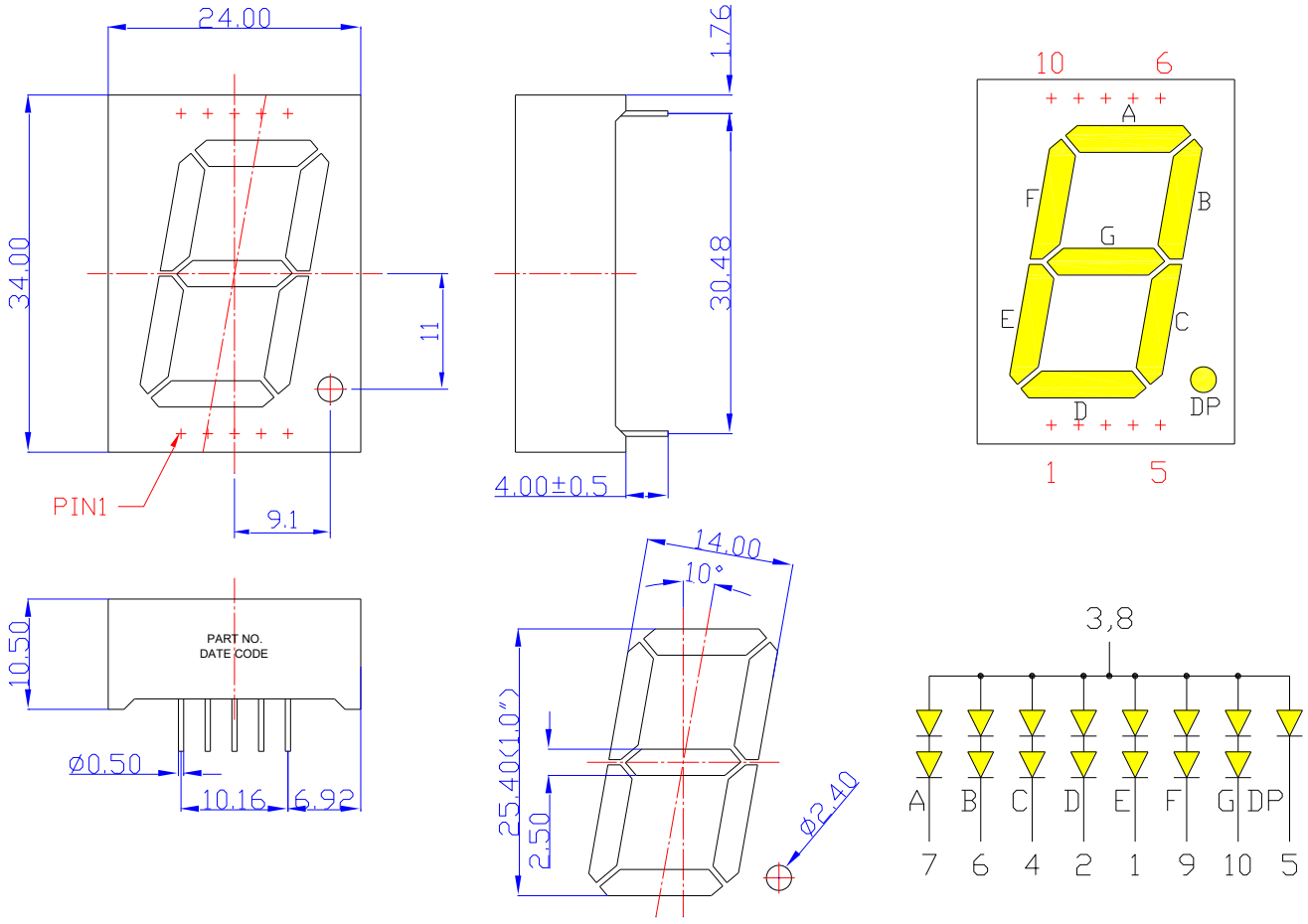
SPECIFICATIONS CDSA10Y2WF

OUTLINES DIMENSIONS



Notes:
1. All Dimensions are in millimeters (inches).
2. Tolerance is ± 0.25mm (0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Description
CDSA10Y2WF	InGaAlP	Yellow	White Segment	Common Anode

ABSOLUTE MAXIMUM RATINGS (TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	P_D	70	mW
Pulse Forward Current	I_{FP}	90	mA
Continuous Forward Current	I_F	25	mA
Reverse Voltage per dice	V_R	5	V
Operating Temperature Range	T_{OPR}	-25~+85	°C
Storage Temperature Range	T_{STG}	-25~+85	°C
I_{FP} = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec			

OPTICAL-ELECTRICAL CHARACTERISTICS (TA=25°C)

Parameter	Symbol	Test Condition	Value			Unit
			Min	Typ	Max	
Luminous Intensity	Iv	I_F = 20mA	-	90	-	mcd
Forward Voltage	V_F	I_F = 20mA	-	4.0	5.2	V
Reverse Leakage Current	I_R	V_R = 5V	-	-	10	μA
Peak Wavelength	λp	I_F = 20mA	-	593	-	nm
Dominant Wavelength	λd	I_F = 20mA	-	590	-	nm
Spectral Line half-width	Δλ	I_F = 20mA	-	20	-	nm

OPTICAL CHARACTERISTIC CURVES

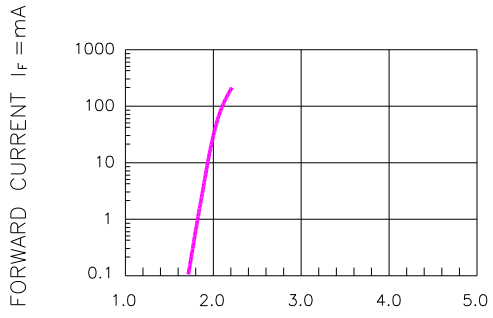


Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE

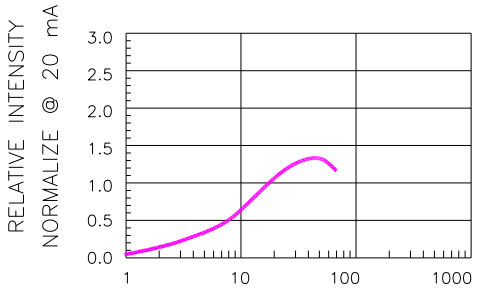


Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT

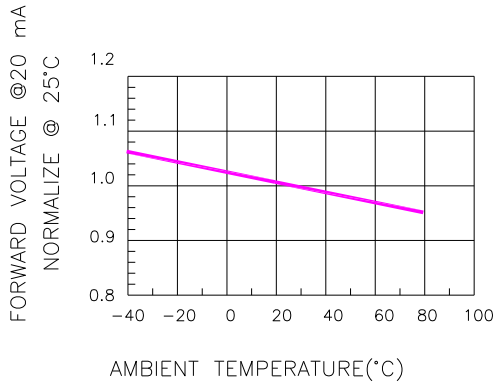


Fig.3 FORWARD VOLTAGE VS. TEMPERATURE

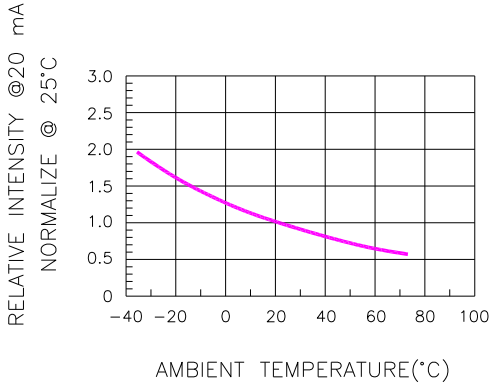


Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

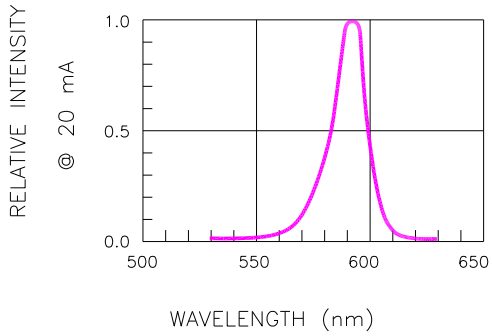


Fig.5 RELATIVE INTENSITY VS. WAVELENGTH

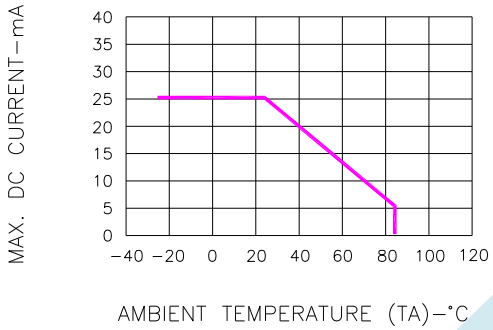
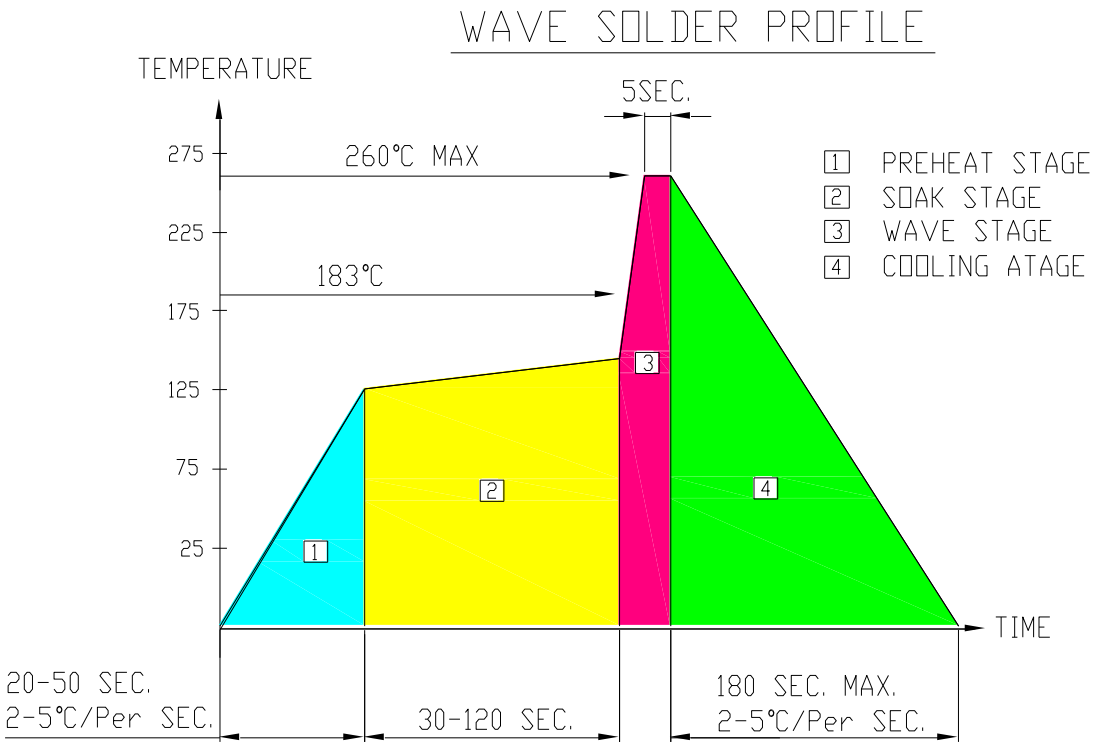


Fig.6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE

SOLDERING CONDITIONS – DISPLAY TYPE LED

RECOMMEND SOLDERING PROFILE



Note:

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- Peak wave soldering temperature between 245°C ~ 225°C for 3 sec (5 sec max)
- No more than one wave soldering pass

SOLDERING IRON

Basic spec is ≦4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.